

5 Ø / Descriptions

Ÿ% ° Ö Æ â k F g 9 y < d < k 3 g v y ' k V " 9 3 ' , / x o
Surface Mount Superfast Recovery Rectifier, Reverse Voltage: 50 to 600V, Forward Current: 3A, SMAF thin package.

/“ / Features

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} o
Glass Passivated Chip Junction “ Superfast reverse recovery time “ Lead free in comply with EU R 2HS 2011/65/EU directives “ For surface mounted applications, HF Product.

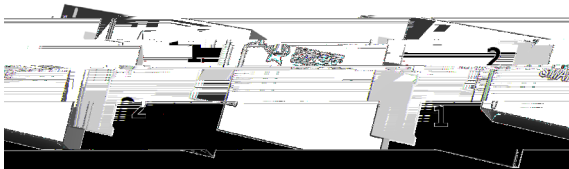
— ÷ / Applications

% † " (o
General purpose.

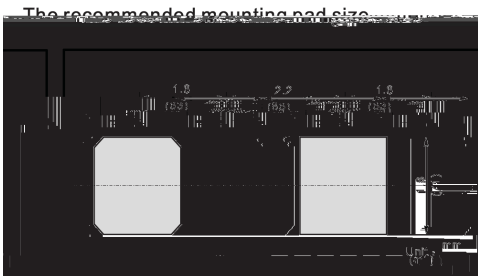
^ W] Ô / Equivalent Circuit



Û æ / Pinning



PIN	DESCRIPTION
1	Cathode
2	Anode



, M V / Marking

- ~ “ ¢ o
See Marking Instructions.

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Electrical Characteristic Curve

Fig.1 Reverse Recovery Time Characteristic And Test Circuit Diagram

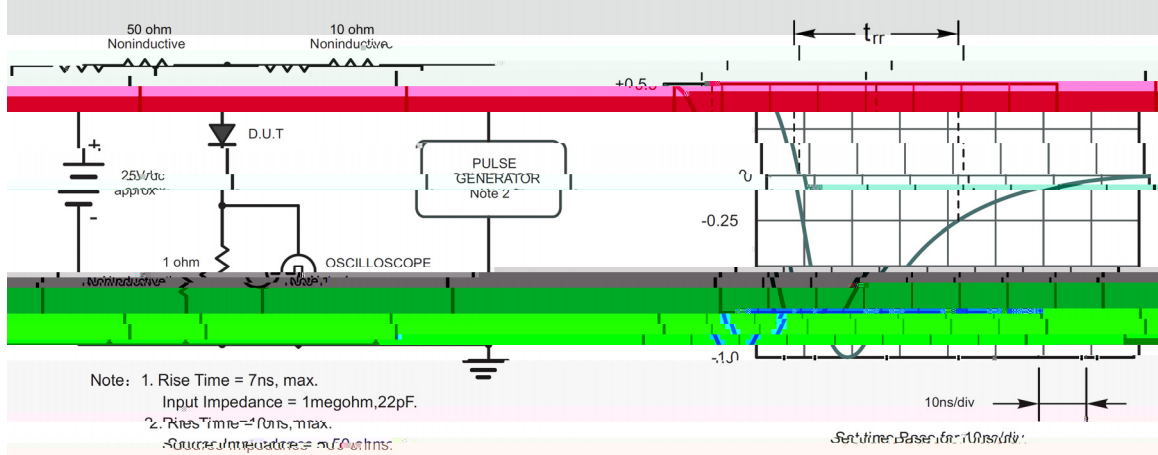


Fig.1 Forward Current Derating Curve

Fig.2 Typical Reverse Characteristics

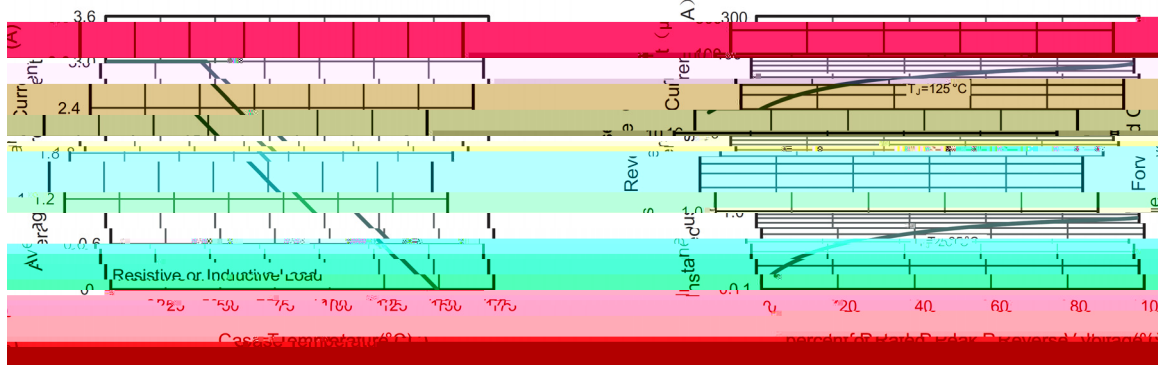


Fig.3 Typical Forward Characteristics

Fig.4 Typical Switching Characteristics

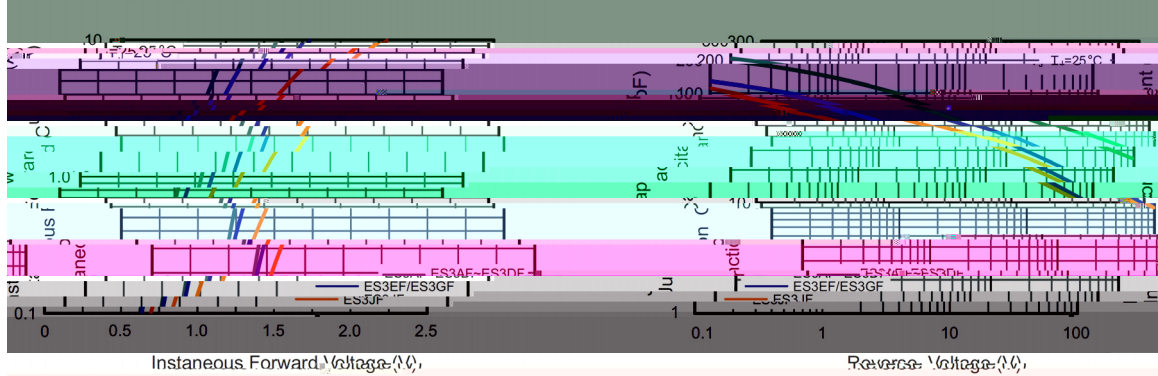
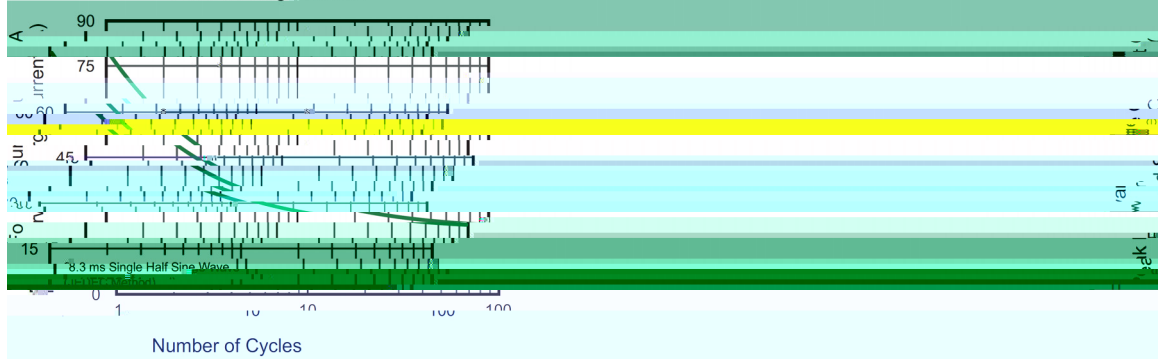
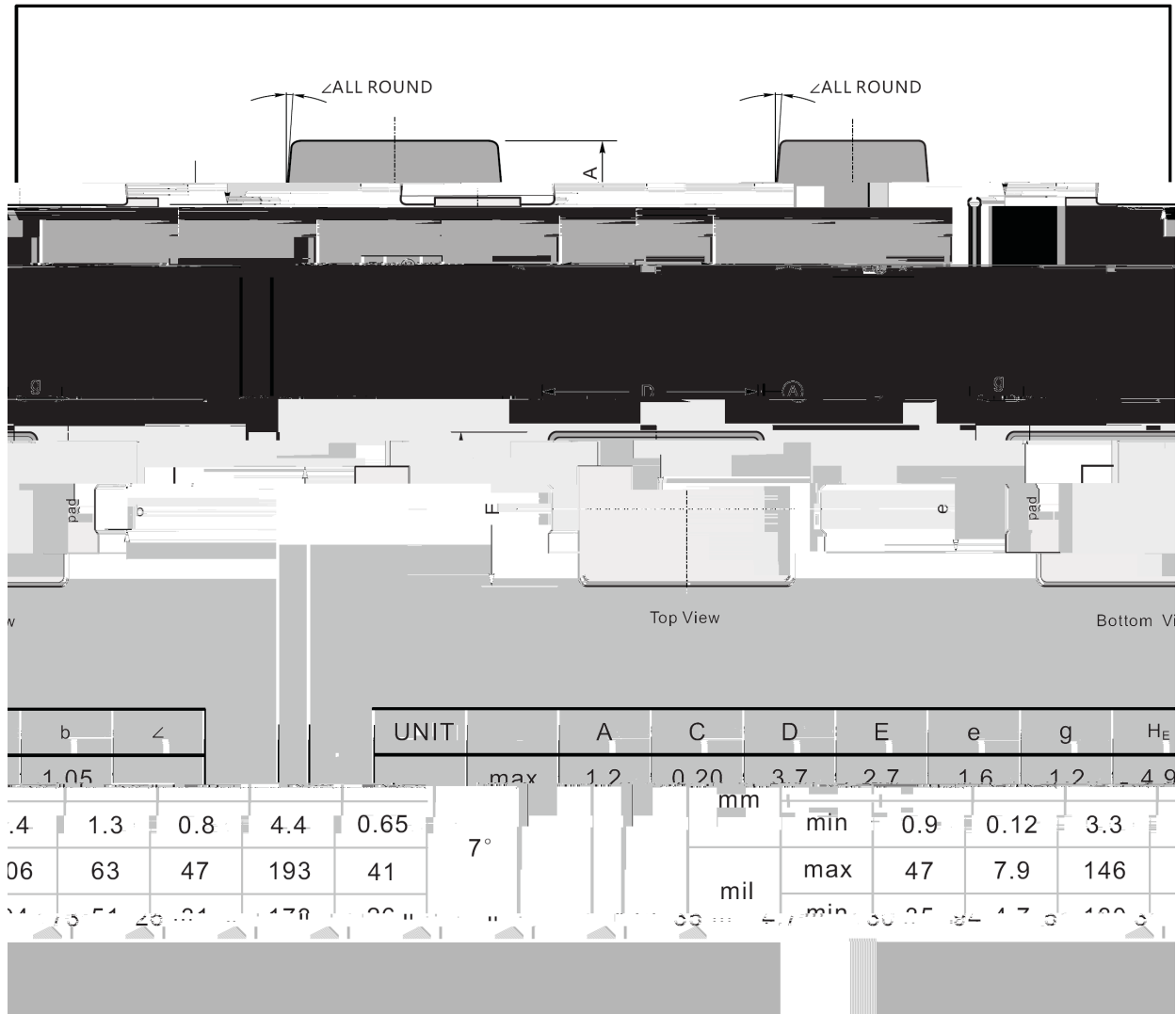


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current



Ø =) ¢ / Package Dimensions



WD t ¢ (x /) / :KSVKXGZ[XK 6XULORK LUX /8 8KLRU] 9URJKXOTM 6

“ ¢ y

1o ~ % 150 %180 - k 60 %90sec;
2o Q 245 r5 - k 4 Ò 5 r0.5sec;
3o D N òi Ò , 2 %10 - /sec.

Note:
1.Preheating:150~180 - , Time:60~90sec.
2.Peak Temp.:245 r5 - , Duration:5 r0.5sec.
3. Cooling Speed: 2~10 - /sec.

´D /Cª p fl »] / Resistance to Soldering Heat Test Conditions

605 r5 - (/ -5.7(Packagling)24286(SPEC.()J/T7 1 Tf03.4485 32.3713 TD.0004 Tc-35.65309:6025130